

Features

- This series is designed for average power 320W approximated ESD protection, different V_{RWM} , different peak pulse power available.
- Protects one I/O or power line.
- Low clamping voltage.
- Working voltages: 3.3V, 5.0V, 12V, 15V, 18V, 24V, 36V.
- Low leakage current.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Compliant to Halogen-free.
- Suffix "-Q1" for AEC-Q101

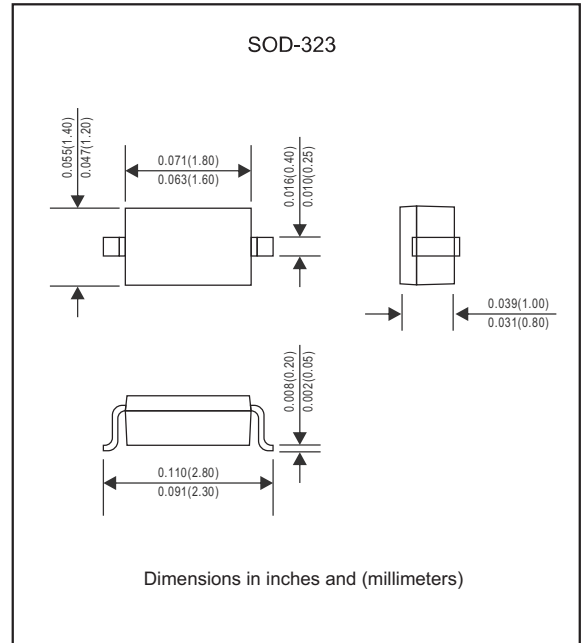
IEC compatibility

- IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- CAN Bus protection

Package outline



Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Maximum ratings (at $T_A=25^\circ C$ unless otherwise noted)

| PARAMETER | CONDITIONS | SYMBOL | VALUE | UNIT |
|--------------------------------------|--|-----------|-------------|------------|
| Total power dissipation | Peak pulse power ($t_p = 8/20\mu s$) | P_{PP} | 320 | W |
| Operating junction temperature range | | T_J | -55 to +125 | $^\circ C$ |
| Storage temperature range | | T_{STG} | -55 to +150 | $^\circ C$ |

Electrical characteristics (at $T_A=25^\circ C$ unless otherwise noted)

| Part No. | V_{RWM} (V) (Max.) | I_R (μA) @ V_{RWM} (Max.) | V_{BR} (V) @ I_T (Min.) | I_T (mA) | V_C (V) @ $I_{PP}=1.0A$ (Max.) | I_{PP} (A) (Max.) | V_C (V) @ I_{PP} (Max.) | C_J (pF) (Max.) |
|--------------|----------------------------|--|-----------------------------------|---------------|--|---------------------------|-----------------------------------|-------------------------|
| ESD3Z3.3C-Q1 | 3.3 | 1 | 3.6 | 1.0 | / | 30.0 | 15.0 | 80 |
| ESD3Z5.0C-Q1 | 5.0 | 1 | 5.5 | 1.0 | 9.0 | 35.0 | 14.0 | 110 |
| ESD3Z12C-Q1 | 12 | 1 | 13.3 | 1.0 | 19.0 | 12.0 | 33.0 | 45 |
| ESD3Z15C-Q1 | 15 | 1 | 16.7 | 1.0 | 23.0 | 10.0 | 33.0 | 40 |
| ESD3Z18C-Q1 | 18 | 1 | 20.0 | 1.0 | 29.0 | 10.0 | 35.0 | 60 |
| ESD3Z24C-Q1 | 24 | 1 | 26.7 | 1.0 | 40.0 | 8.0 | 50.0 | 35 |
| ESD3Z36C-Q1 | 36 | 0.2 | 40.0 | 1.0 | 60.0 | 6.0 | 70.0 | 25 |

Typical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1: V - I curve characteristics (Bi-directional)

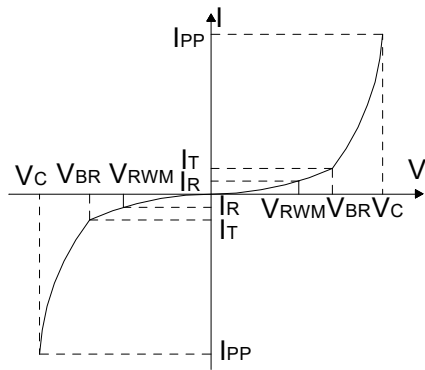


FIG.2: Pulse waveform (8/20 μs)

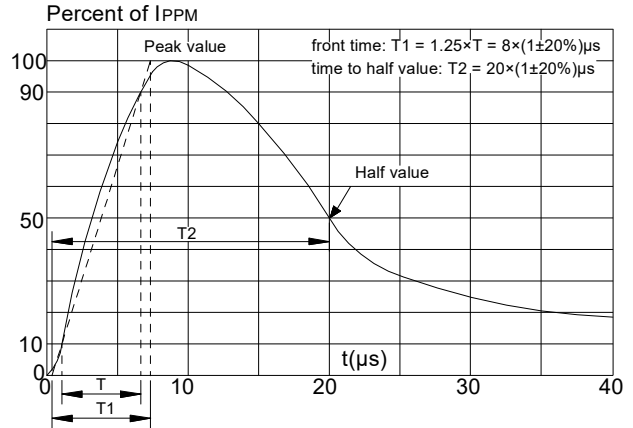


FIG.3: Pulse derating curve

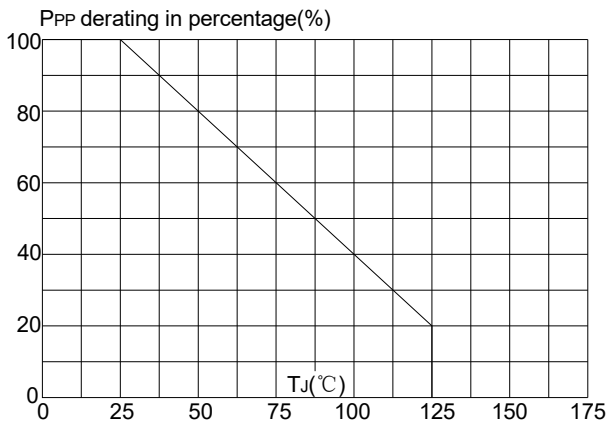
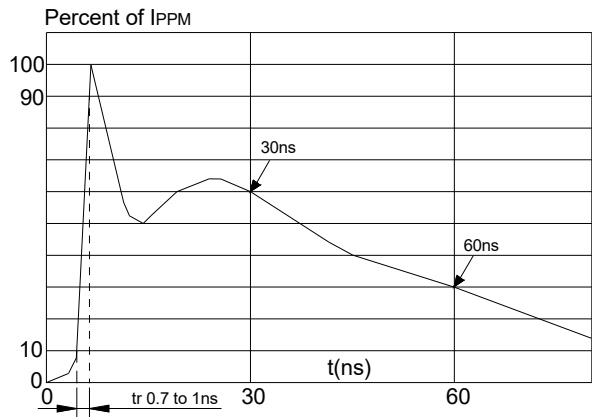




FIG.4: ESD clamping (30kV contact)



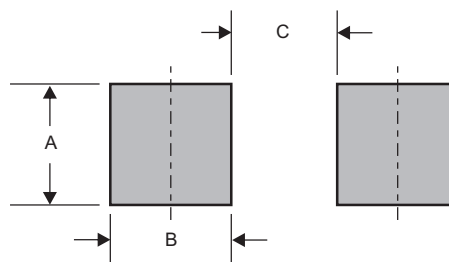
Pinning information

| Pin | Simplified outline | Symbol |
|----------------|---|---|
| Bi-Directional |  |  |

Marking

| Type number | Marking code |
|--------------|--------------|
| ESD3Z3.3C-Q1 | 03B/33L |
| ESD3Z5.0C-Q1 | 05B/3M |
| ESD3Z12C-Q1 | 12B/12C |
| ESD3Z15C-Q1 | 15B/2J |
| ESD3Z18C-Q1 | 18B./18C |
| ESD3Z24C-Q1 | 24B/M |
| ESD3Z36C-Q1 | 2N |

Suggested solder pad layout



Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|---------|--------------|--------------|--------------|
| SOD-323 | 0.033 (0.83) | 0.025 (0.63) | 0.063 (1.60) |